

Abstract

A HEAT SINK ASSEMBLY FOR INTEGRATED CIRCUITS HAVING
A SLIDABLE CONTACT CAPABILITY WITH A MOUNTING MEMBER PORTION
OF AN ELECTRONIC EQUIPMENT CHASSIS

The heat sink assembly includes a heat sink member with a body portion and an upper mounting portion. The heat sink member is connected to an integrated circuit on a printed circuit board assembly. A resilient mounting assembly is positioned on the mounting portion of the heat sink assembly and is constructed and arranged to permit the heat sink assembly to be removably mounted on the mounting member, which in turn is attachable to or part of the chassis of the electronic equipment. The mounting assembly includes a bias element, such as a spring, for holding the heat sink assembly and the mounting member together in a low thermal resistance relationship.